

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (canceled)
2. (currently amended) An apparatus comprising:
 - a substrate;
 - a pair of signal traces formed directly on the substrate and spaced from each other;
 - a filler material directly on the substrate and between the signal traces, the filler material having a dielectric constant that is higher than a dielectric constant of a material of which the substrate is formed; and
 - a solder mask layer on the signal traces and on the filler material, the dielectric constant of the filler material being higher than a dielectric constant of the solder mask layer.
3. (previously presented) The apparatus of claim 2, wherein the substrate includes a resin in which fibers are embedded, the dielectric constant of the filler material being higher than a dielectric constant of the resin.
4. (previously presented) The apparatus of claim 2, wherein the signal traces are formed of copper.
5. (previously presented) The apparatus of claim 2, wherein the filler material substantially fills a space between the signal traces.

6. (previously presented) The apparatus of claim 2, wherein the filler material has a height that is substantially equal to a height of the signal traces.

7. (previously presented) The apparatus of claim 2, wherein the filler material has a dielectric constant in excess of 4.

8-28 (canceled)

29. (previously presented) The apparatus of claim 2, wherein the filler material includes polyvinylidene difluoride.